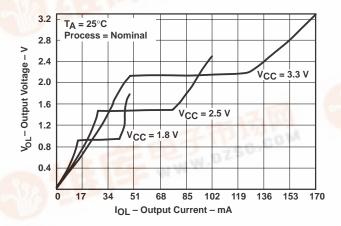
SCES154G - DECEMBER 1998 - REVISED FEBRUARY 2000

- Member of the Texas Instruments
 Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC[™] (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications

- I_{off} Supports Partial-Power-Down Mode Operation
- Ideal for Use in PC133 Registered DIMM Applications
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC*TM) *Circuitry Technology and Applications*, literature number SCEA009.



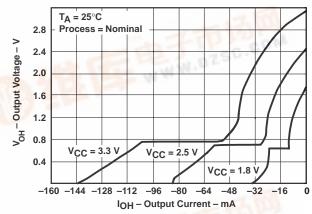


Figure 1. Output Voltage vs Output Current

This 16-bit universal bus driver is operational at 1.2-V to 3.6-V $_{\rm CC}$, but is designed specifically for 1.65-V to 3.6-V $_{\rm CC}$ operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (\overline{LE}) input is low. When \overline{LE} is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If \overline{LE} is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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SN74AVC16334 16-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

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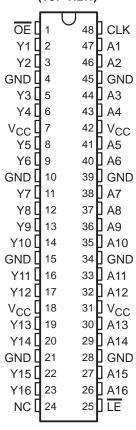
description (continued)

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16334 is characterized for operation from -40°C to 85°C.

terminal assignments

DGG OR DGV PACKAGE (TOP VIEW)



NC - No internal connection

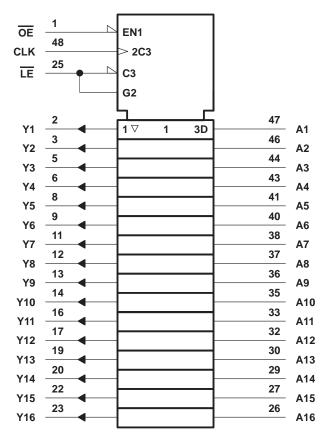
FUNCTION TABLE (each universal bus driver)

	INPUTS							
OE	LE	CLK	Α	Υ				
Н	Χ	Х	Χ	Z				
L	L	X	L	L				
L	L	X	Н	Н				
L	Н	\uparrow	L	L				
L	Н	\uparrow	Н	Н				
L	Н	L or H	Χ	Y ₀ †				

[†] Output level before the indicated steady-state input conditions were established

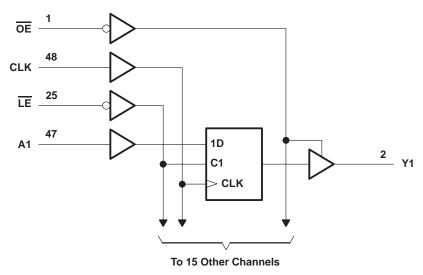


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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bsolute maximum ratings over operating free-air temperature range (unless otherwise noted)†
Supply voltage range, V_{CC}
(see Note 1)
(see Notes 1 and 2)
$\begin{array}{llllllllllllllllllllllllllllllllllll$
Continuous output current, I $_{\rm O}$
Package thermal impedance, θ _{JA} (see Note 3): DGG package
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT		
\/	Cumhusaltaga	Operating	1.4	3.6	V		
vCC.	Supply voltage	Data retention only	1.2		V		
		V _{CC} = 1.2 V	Vcc				
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	0.65 × V _{CC}				
V_{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V		
Data retention only 1.2		1					
		V _{CC} = 3 V to 3.6 V	2	.4 3.6 .2 .2 .2 .2 .3 .4 .4 .2 .2 .5 .7 .7 .2 .5 .7 .2 .5 .7 .0.8 .0 .3.6 .0 .7 .0.8 .0 .3.6 .0 .7 .0.8 .0 .3.6 .0 .0 .0 .0 .0 .0 .0 .0 .0 .0 .0 .0 .0			
		V _{CC} = 1.2 V		GND			
	Low-level input voltage	V _{CC} = 1.4 V to 1.6 V		0.35 × V _{CC}	V		
V_{IL}		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7			
		V _{CC} = 3 V to 3.6 V		0.8			
VI	Input voltage		0	3.6	V		
-	Output voltage	Active state	0	Vcc	V		
۷O	Output voltage	Active state 0 3-state 0	3.6	\ \ \			
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		0.65 × V _{CC} 1.7 2 GND 0.35 × V _{CC} 0.35 × V _{CC} 0.7 0.8 0 3.6 0 V _{CC} 0 3.6 -2 -4 -8 -12 2 4 8 12 5			
1	Static high level cutout current	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-4	A		
OHS	/I Input voltage /O Output voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	mA		
		V _{CC} = 3 V to 3.6 V		GND 0.35 × V _{CC} 0.35 × V _{CC} 0.7 0.8 3.6 V _{CC} 3.6 -2 -4 -8 -12 2 4 8 12 5			
		V _{CC} = 1.4 V to 1.6 V		2			
1	Static law level output outpost	V _{CC} = 1.65 V to 1.95 V		4	A		
IOLS	Static low-level output current	V _{CC} = 2.3 V to 2.7 V		mA			
		V _{CC} = 3 V to 3.6 V		12			
Δt/Δν	Input transition rise or fall rate	V _{CC} = 1.4 V to 3.6 V		5	ns/V		
TA	Operating free-air temperature		-40	85	°C		

[†] Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST C	CONDITIONS	Vcc	MIN	TYP [†]	MAX	UNIT	
		I _{OHS} = -100 μA		1.4 V to 3.6 V	V _{CC} -0.	.2			
		$I_{OHS} = -2 \text{ mA},$	V _{IH} = 0.91 V	1.4 V	1.05				
Vон		$I_{OHS} = -4 \text{ mA},$	V _{IH} = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2.3				
		I _{OLS} = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	$V_{IL} = 0.49 V$	1.4 V			0.4		
VOL		I _{OLS} = 4 mA,	V _{IL} = 0.57 V	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	$V_{IL} = 0.7 V$	2.3 V			0.55		
		I _{OLS} = 12 mA,	V _{IL} = 0.8 V	3 V			0.7		
Ц	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
l _{off}		V_I or $V_O = 3.6 V$		0			±10	μΑ	
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ	
	CLK input	VI – Voo or CND		2.5 V		4			
	CLK Input	$V_I = V_{CC}$ or GND		3.3 V		4			
	Control inputs	V. Vocar CND		2.5 V		4		~F	
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		4		pF	
	Data inpute	V V 0ND		2.5 V		2.5			
	Data inputs	$V_I = V_{CC}$ or GND	3.3 V		2.5				
C	Outputs	V- V or CND		2.5 V		6.5		nE	
Со	σαιραίδ	$V_O = V_{CC}$ or GND		3.3 V		6.5		pF	

[†] Typical values are measured at $T_A = 25$ °C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

			V _{CC} = 1.2 V		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock freq	uency							150		150		150	MHz	
	Pulse	LE low						3.3		3.3		3.3		ns	
t _W	duration	CLK high or low						3.3		3.3		3.3		115	
	Setup time	Data before CLK↑		1		0.8		0.7		0.7		0.7			
t _{su}			Data	CLK high	1.5		1.4		0.9		0.9		0.9		ns
		before LE↑	CLK low	2.7		1.6		1.2		1		1			
t _h	Hold time	Data after CLK↑		1.3		1.1		0.9		0.8		0.7		ns	
+.	Hold	Hold Data	CLK high	2.2		1.9		1.7		1.5		1.5		ns	
t _h	time	time	after LE↑	CLK low	2.4		1.8		1.6		1.4		1.3		ns



switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

PARAMETER	FROM TO (OUTPU	_	1 **		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V	
		(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}						150		150		150		MHz
	Α	Y	5.3	1.2	6.2	1.5	4.9	1	3.2	0.9	2.5	
t _{pd}	LE		7	2.2	9.7	1.8	7.5	1.5	4.9	0.8	4	ns
	CLK		6	1.9	7.8	1.6	6	1.1	3.7	1	3.1	
t _{en}	ŌĒ	Υ	7.9	2.4	10.2	1.6	8.8	1.5	6.7	1	6.2	ns
^t dis	ŌĒ	Y	7.7	2.1	10.3	1.5	8.4	1.2	5.3	1	5.3	ns

switching characteristics, T_A = 0°C to 85°C, C_L = 0 pF †

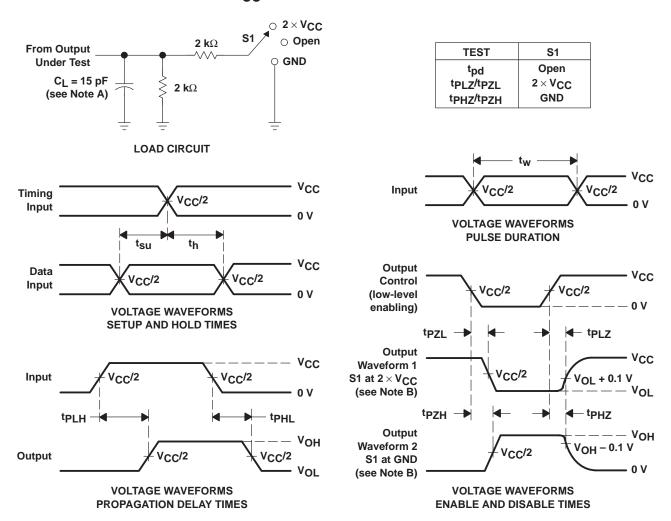
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1	UNIT	
	(INFOT)	(001701)	MIN	MAX	
	А	V	0.6	1.3	
^t pd	CLK	7 F	0.7	1.5	ns

[†] Texas Instruments SPICE simulation data

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST C	ONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
	FARAIVIETER		1231 0	ONDITIONS	TYP TYP		TYP	ONIT	
	Power dissipation	Outputs enabled	C 0	f = 10 MHz	45	48	52	ne ne	
Cpd	capacitance	Outputs disabled	$C_L = 0$,		23	25	28	pF	

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.2 \text{ V}$ AND 1.5 V \pm 0.1 V



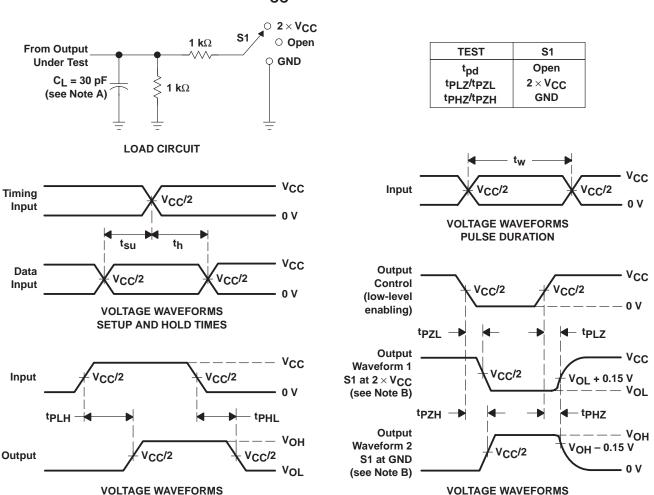
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{\mbox{\scriptsize 0}}$ = 50 $\Omega,\,t_{\mbox{\scriptsize f}}\leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.

PROPAGATION DELAY TIMES

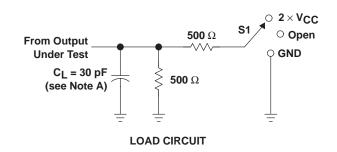
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

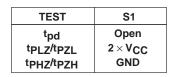
Figure 3. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

Input





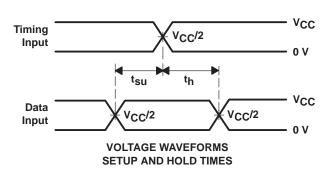
V_{CC}/2

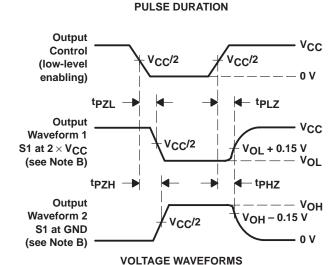
VOLTAGE WAVEFORMS

VCC

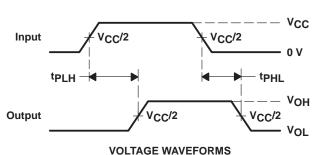
0 V

V_{CC}/2





ENABLE AND DISABLE TIMES



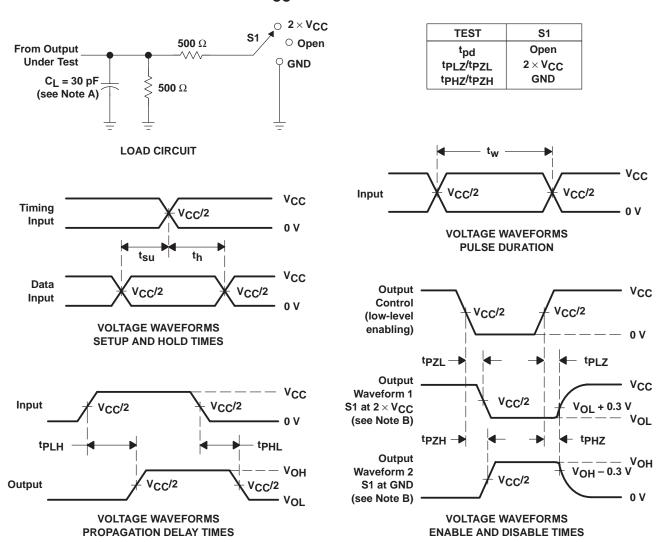
PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2 \ ns$, $t_f \leq 2 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



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